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1. (currently amended) A multi-layer semiconductor chip package, comprising:  
a first plurality of pairs of conductors for carrying a plurality of first signals in a layer of a carrier of the package, and, wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors overlap each other evenly, wherein  
a second pair of conductors for carrying a second signal adjacent to the first pair of conductors in the layer, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.
5. (currently amended) The package of claim [4] 1, wherein the first and second adjacent pairs of conductors are positioned orthogonally to each other.
6. (currently amended) The package of claim [4] 1, wherein the second adjacent pairs of conductors is ~~are~~ positioned to be equidistant to each other conductor in the first pair of conductors.
7. (original) The package of claim 1, wherein the layer is near an interface between the carrier and a chip.

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15. (currently amended) A connector capable of being coupled to a semiconductor chip package, comprising:

a first plurality of pairs of conductors for carrying a plurality of first signals in a layer of a carrier of the package; and, wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors affect each other evenly, wherein

a second pair of conductors for carrying a second signal adjacent to the first pair of conductors, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.

17. (currently amended) The connector of claim 16 15, wherein the second adjacent pairs of conductors is are positioned to be equidistant to each other conductor in the first pair of conductors.

18. (currently amended) A method for providing a semiconductor chip package, comprising the steps of:

(a) providing a first plurality of pairs of conductors for carrying a first plurality of signals in a layer of a carrier of the package; and, wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors affect each other evenly, wherein

(b) —providing a second pair of conductors for carrying a second signal adjacent to the

first pair of conductors in the layer, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.

22. (currently unended) The method of claim 24 18, wherein the second adjacent pairs of conductors is are positioned to be equidistant to each other conductor in the first pair of conductors.

23. (original) The method of claim 18, wherein the layer is near an interface between the carrier and a chip.